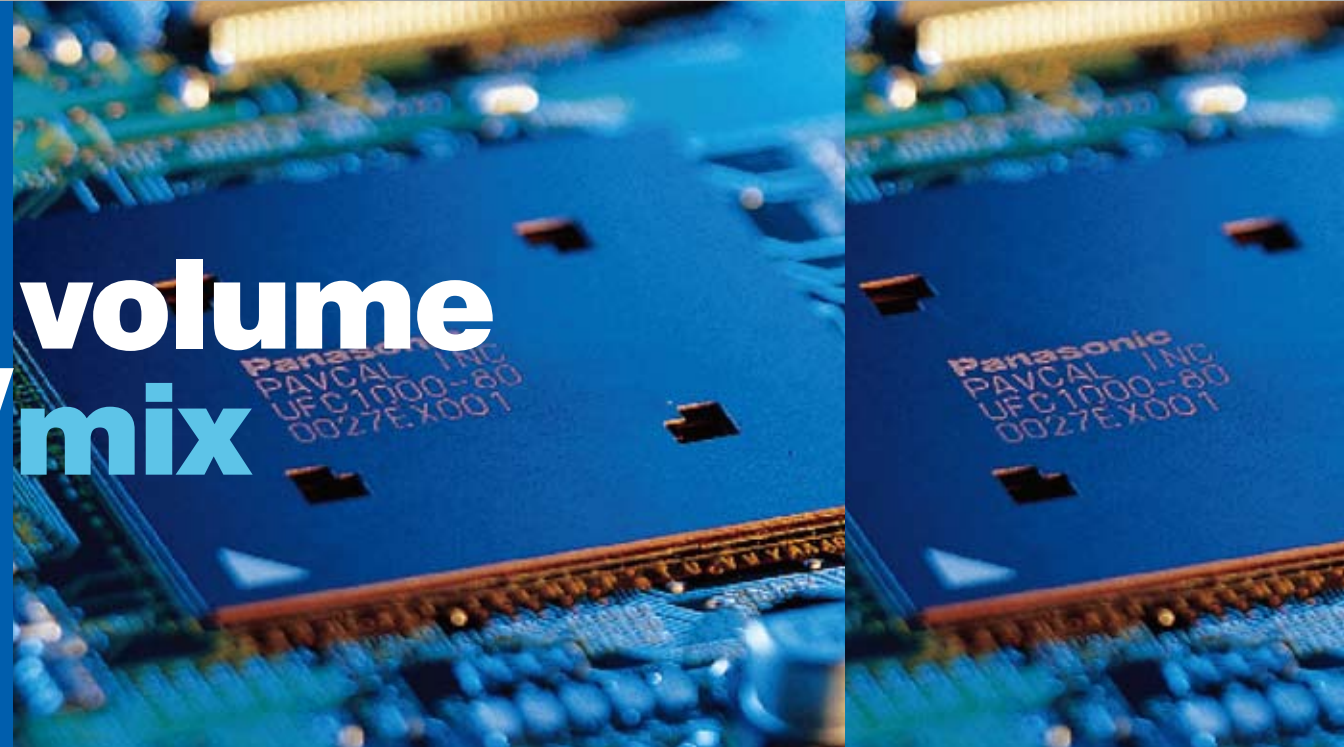




Our Solutions, Your Value

any volume  
any mix



NM-EJM8B

\*A feeder cart is an optional.

**⚠ Safety Cautions**

● Please read the User's Manual carefully to familiarize yourself with safe and effective usage procedures.

● To ensure safety when using this equipment all work should be performed according to that as stated in the supplied Operating Instructions. Read your operating instruction manual thoroughly.

**eco ideas**

Panasonic Group products are built with the environment in mind.  
<http://panasonic.net/eco/>

**ISO 14001**

Panasonic Group builds Environmental Management System in the factories of the world and acquires the International Environmental Standard ISO 14001:2004.

Inquiries...

**Panasonic Factory Solutions Co., Ltd.**  
Corporate Sales Division

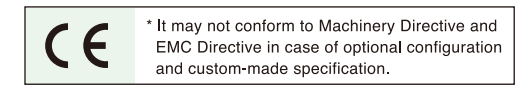
1375 Kamisukiawara, Showa-cho, Nakakoma-gun, Yamanashi 409-3895, Japan  
TEL +81-55-275-9148  
FAX +81-55-275-6269

**All data as of December 1, 2011**  
Ver. December 1, 2011

**BM series**  
 Model No. NM-EJM6B, NM-EJM7B, NM-EJM8B, NM-EJM1C

### ●Modular Placement Machine

●This compact machine inherits the latest technology of Panasonic, and realizes the outstanding productivity, reliability and economical efficiency.



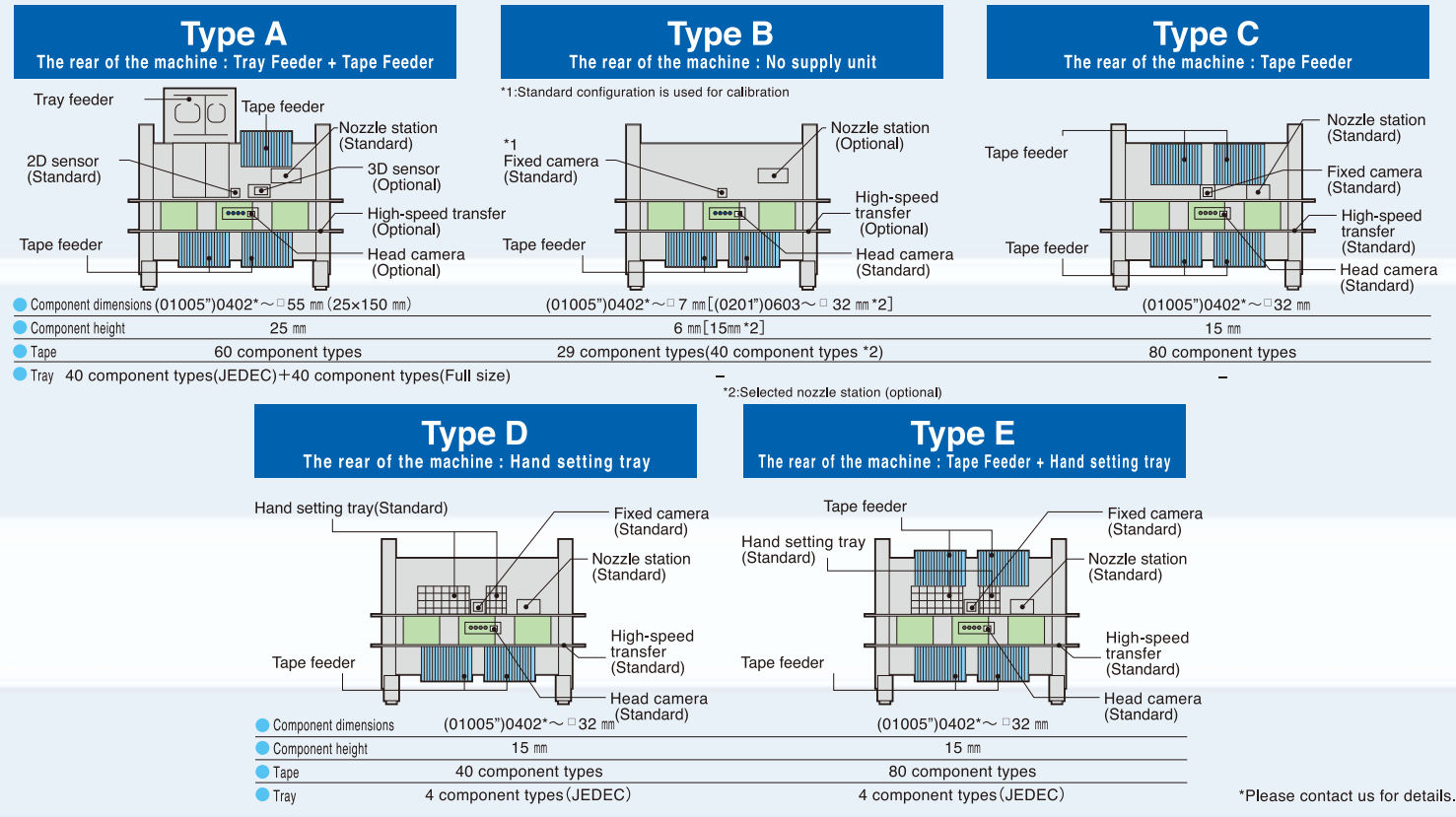
	Type A		BM221	BM231
Model ID	BM123	BM133	BM221	BM231
Model No.	NM-EJM6B	NM-EJM7B	NM-EJM8B	NM-EJM1C
PCB dimensions (mm)	L 50 × W 50 to L 330 × W 250	L 50 × W 50 to L 510 × W 460	L 50 × W 50 to L 330 × W 250	L 50 × W 50 to L 510 × W 460
Max. speed	0.12 s/chip		0.25 s/chip	
Placement accuracy	± 50 μm/Chip (Cpk≥1) 、 ± 30 μm/QFP (Cpk≥1)			
No. of component inputs	80 (Double tape feeder:160)		60 (Double tape feeder:120), Tray:80	
Component dimensions (mm) *1	(01005") 0402 *7 chip to L 32 × W 32 × T 15		(01005") 0402 *7 chip to L 150 × W 25 × T 25 or L 55 × W 55 × T 25	
PCB exchange time*2	2.5 s *5	5.0 s	2.5 s (High-speed transfer specification configuration,*6)	5.0 s
Electric source	3-phase AC 200, 220, 380, 400, 420, 480 V 1.0 kVA			
Pneumatic source	0.43 MPa, 150 L/min (A.N.R.)			
Dimensions (mm)	W 1 950 × D 1 500 *3 × H 1 500 *4	W 1 950 × D 1 710 *3 × H 1 500 *4	W 1 950 × D 2 060 *3 × H 1 500 *4	W 1 950 × D 2 270 *3 × H 1 500 *4
Mass*5	1 700 kg	1 800 kg	2 000 kg	2 100 kg

\*Values such as maximum speed and placement accuracy may vary depending on operating conditions.  
 \*Please refer to the "Specification" booklet for details.  
 \*1:Varies depending on selectable Specifications.  
 \*2:It varies depending on the specification of PCBs.  
 \*3:Excluding batch exchange cart and tape feeder.  
 \*4:Excluding recognition monitor and signal tower.  
 \*5:Fixed component supply unit specification  
 When including a feeder cart : BM123: 2 100 kg BM221: 2 200 kg.  
 BM133: 2 200 kg BM231: 2 300 kg.  
 \*6:When no components are placed on the back of the PCB.  
 \*7:Please contact us for details.



A variation of available options for the supply unit [BM221]

# right-sized solutions for world-class manufacturing



A wide range of component

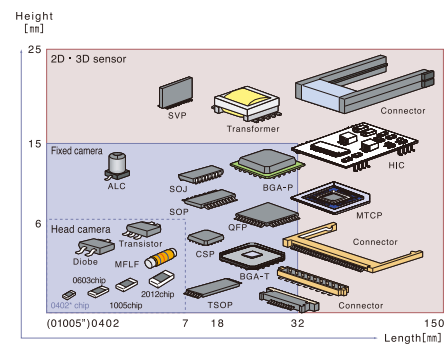
Quick changeover capabilities

Fast, accurate placement

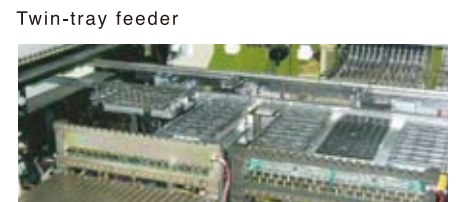
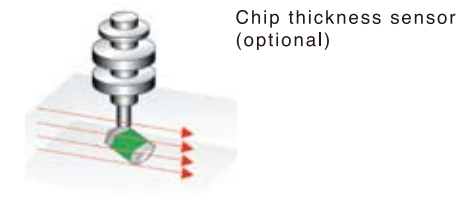
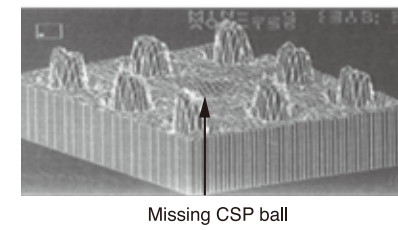
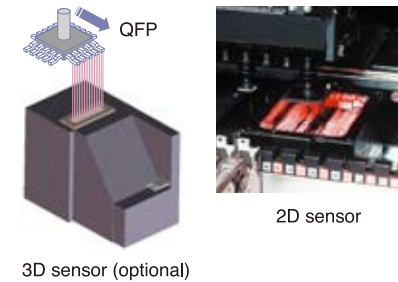
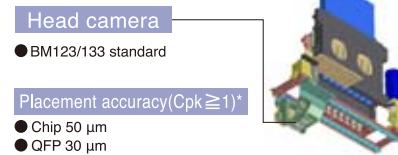
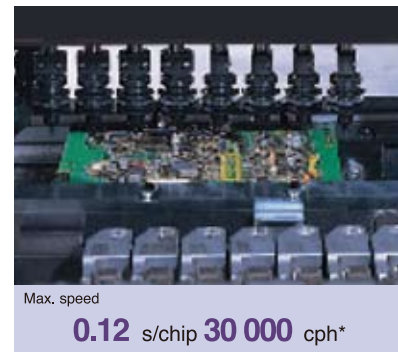
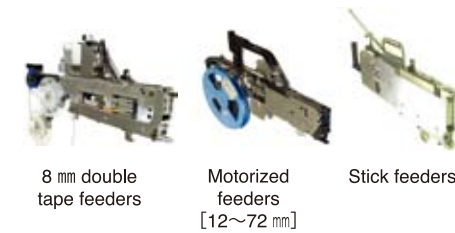
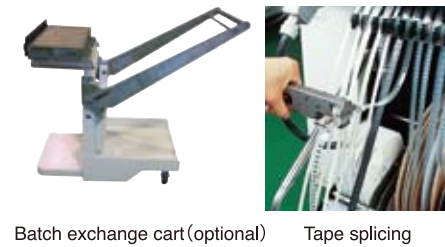
3D camera (optional)

Chip thickness measuring sensor (optional)

Direct tray support function



	Head camera	Fixed camera	2D sensor	3D sensor
BM123.133	Standard	Standard	—	—
BM221	Type A	Optional	—	Standard
	Type B,C,D,E	Standard	Standard	—
BM231	Optional	—	Standard	Optional



Ensures continuous productivity by placing components from (01005\*)0402\* to L 55 mm × W 55 mm or L 150 mm × W 25 mm components on tape, reel and tray. The BM221 & 231 offer productivity with up to 120 tape and 80 tray (JEDEC standard) inputs.

Quick changeover capabilities include:

- Batch exchange cart
- Motorized feeders
- Tape splicing (Component supply during operation)
- Optimized software

The 8-nozzle vertical drive provides batch recognition and batch pick-up for components in variable heights.  
\*It differs depending on the condition.

2D and 3D sensors are used to accurately place components ranging from microchips to L 55 mm × W 55 mm × T 25 mm, QFPs, BGAs and CSPs.

The chip thickness sensor measures the thickness of components to improve placement quality.

QFP and odd-shape components can be continuously supplied at high speed using twin-tray feeders. (BM221 and BM231) Also, a hand setting tray table can be selected. (BM221)

\*Please contact us for details.